SCBS199C - FEBRUARY 1991 - REVISED MAY 1997

- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **High-Impedance State During Power Up** and Power Down
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **Package Options Include Plastic** Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

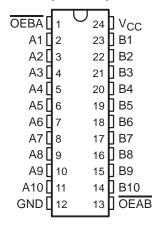
The 'ABT861 are 10-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

devices allow noninverted These transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

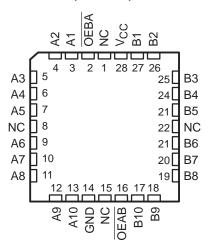
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT861 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT861 is characterized for operation from -40°C to 85°C.

SN54ABT861 . . . JT PACKAGE SN74ABT861...DW OR NT PACKAGE (TOP VIEW)



SN54ABT861 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



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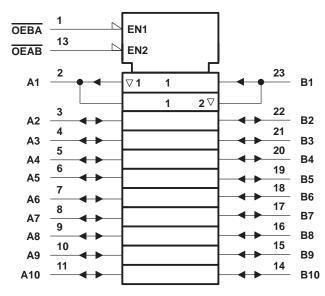
EPIC-IIB is a trademark of Texas Instruments Incorporated.



FUNCTION TABLE

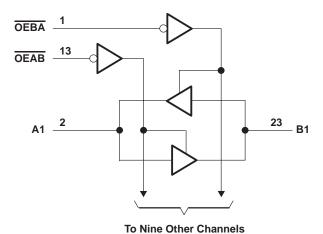
INP	UTS	ODED ATION
OEAB	OEBA	OPERATION
L	Н	A data to B bus
Н	L	B data to A bus
Н	Н	Isolation
L	L	Latch A and B (A = B)

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT861	96 mA
SN74ABT861	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54AI	BT861	SN74A	BT861	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EM	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0 <	Vcc	0	VCC	V
IOH	High-level output current		ζ)	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	A.	5		5	ns/V
TA	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SN54ABT861, SN74ABT861 10-BIT TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COL	UDITIONS	Т	A = 25°C	;	SN54A	BT861	SN74ABT861		UNIT	
PARAIVIE	IEK	TEST COM	ADITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\ \/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				·	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
Contr	ol inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μА	
I A or E	3 ports	VCC = 5.5 V,	AL = ACC OLGIAD			±100		±100		±100	μΑ	
lozpu [‡]		$\frac{V_{CC}}{OE} = 0$ to 2.1 V, V _C	y = 0.5 V to 2.7 V,			±50		±50		±50	μА	
l _{OZPD} ‡		$\frac{V_{CC}}{OE} = 2.1 \text{ V to } 0, V_{CC}$) = 0.5 V to 2.7 V,			±50		±50		±50	μА	
I _{OZH} §		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50	S	50		50	μΑ	
I _{OZL} §		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50	Q _C	- 50		- 50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	d _d			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μА	
IO¶		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-225 [#]	-50	-225 [#]	-50	-225#	mA	
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μΑ	
ICC A or E	3 ports	$I_{O} = 0$,	Outputs low		24	38		38		38	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ	
Data	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	Outputs enabled			1.5		1.5		1.5		
			Outputs disabled			1.5#		1.5#		1.5#	mA	
Control inputs		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5		
C _i Contr	ol inputs	V _I = 2.5 V or 0.5 V			4.5						pF	
C _{io} A or E	3 ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			10.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#] This limit may vary among suppliers.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

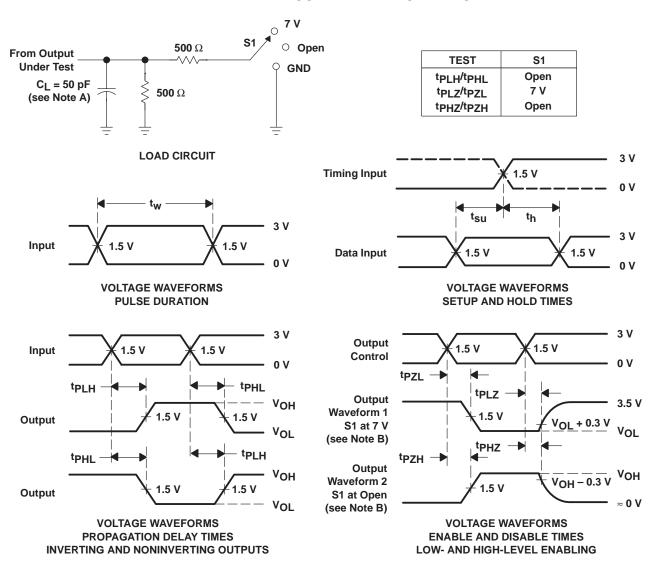
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54A	BT861	SN74ABT861		UNIT
	(INFOT)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1	3.4	4.9	1	5.3	1	5.2	ns
tPHL	AOIB	BULK	1	3.2	4.4	1	5	1	4.9†	1115
^t PZH	OEAB or OEBA	B or A	1	3.5	5	1,	6	1	5.9	ns
tPZL	OEAB OF OEBA	BULA	1	4.6	6	37)	7	1	6.9	110
^t PHZ	OF A D OF D A	B or A	2.1	5.3	6.5	2.1	7.6	2.1	7.5	
t _{PLZ}	OEAB or OEBA	BULK	1.5	5.3	6.6	1.5	7.2	1.5	7.1	ns

[†] This limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SN74ABT861DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT861
SN74ABT861DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT861

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

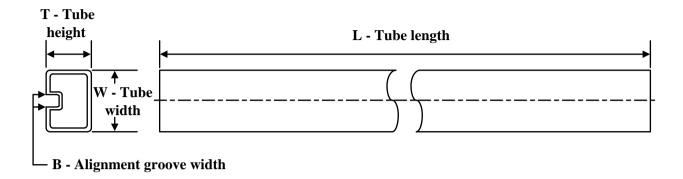
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

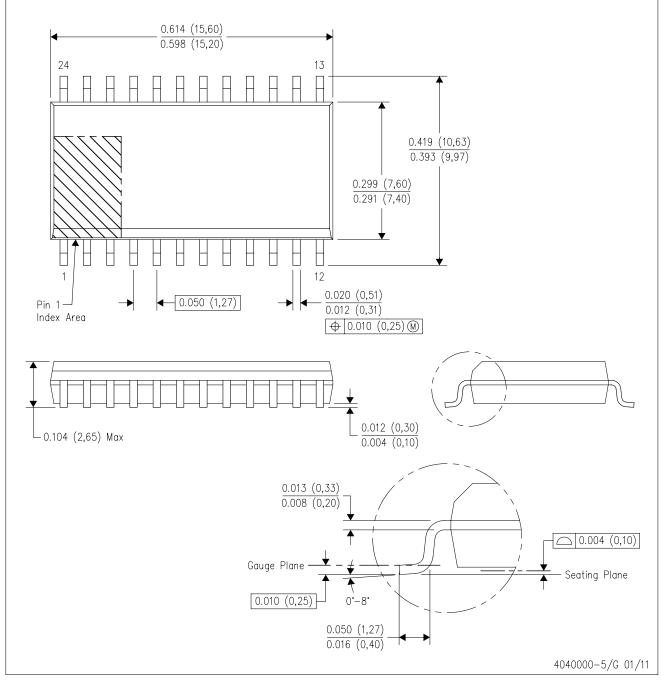


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT861DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT861DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



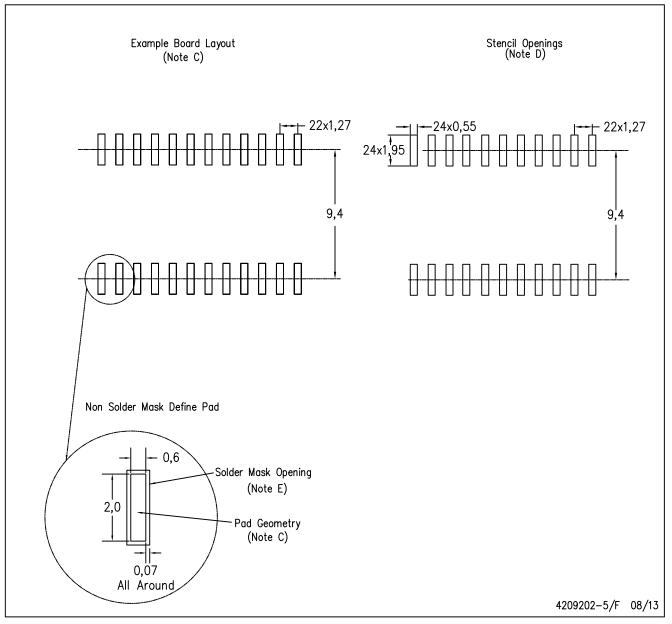
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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